LV10200D

Rev.F May.-2016

蓝箭电子 BLUE ROCKET ELECTRONICS

DATA SHEET

/ Descriptions

TO-252

Schottky Barrier Diode in a TO-252 Plastic Package.

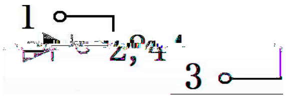
/ Features

High Forward Surge Capability, Ultra Low Forward Voltage Drop, Excellent High Temperature Stability.

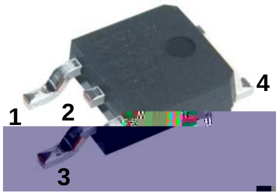
/ Applications

For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications.

/ Equivalent Circuit



/ Pinning



PIN1	Anode	PIN 2,4	Cathode	PIN 3	Anode

/ h_{FE} Classifications & Marking

See Marking Instructions.

/ Absolute Maximum Ratings(Ta=25)

Parameter	Symbol	Rating	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage Peak Reverse Voltage	V_{RRM} V_{RWM} V_{RM}	200	V
RMS Reverse Voltage	$V_{R(RMS)}$	140	V
Average Rectified Forward Current	$I_{F(AV)}$	10	A
Non Repetitive Peak Surge Current	I_{FSM}	150	A
Junction Temperature Range	$T_{j\ MAX}$	150	
Storage Temperature Range	T_{stg}	-55 150	

Parameter	Symbol	Test Conditions		Min	Typ	Max	Unit
Reverse Voltage	V_{BR}	I_R=0.3mA		200			V
Forward Voltage	V_F	I_F=2A	T_J=25		0.68	0.75	V
		I_F=2A	T_J=125		0.53	0.58	V
		I_F=10A	T_J=25		0.87	0.95	V
		I_F=10A	T_J=125		0.70	0.75	V
Instantaneous Reverse Current	I_R Note 1	V_R=200V	T_J=25		4	20	uA
		V_R=150V	T_J=125		1.9	5	mA
		V_R=200V	T_J=125		3.5	10	mA

/Notes

1. /Short duration pulse test used to minimize self-heating effect.

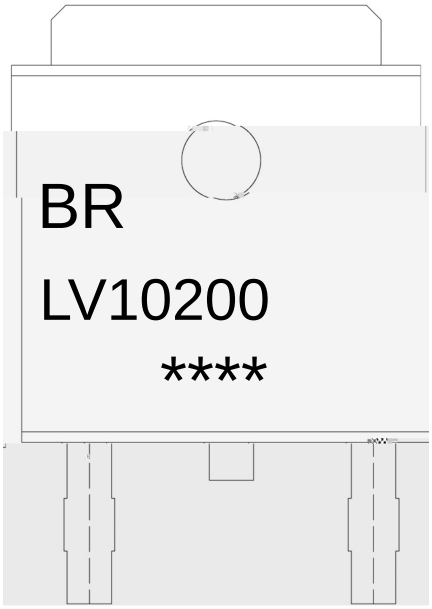
/ Package Dimensions

00	0. 10

c	0.45	0.55	L2	1.25
D	6.45	6.75	L3	0.6
D1	5. 10	5. 50	K	0.

TO-252

/ Marking Instructions



BR

10200

LV TBR

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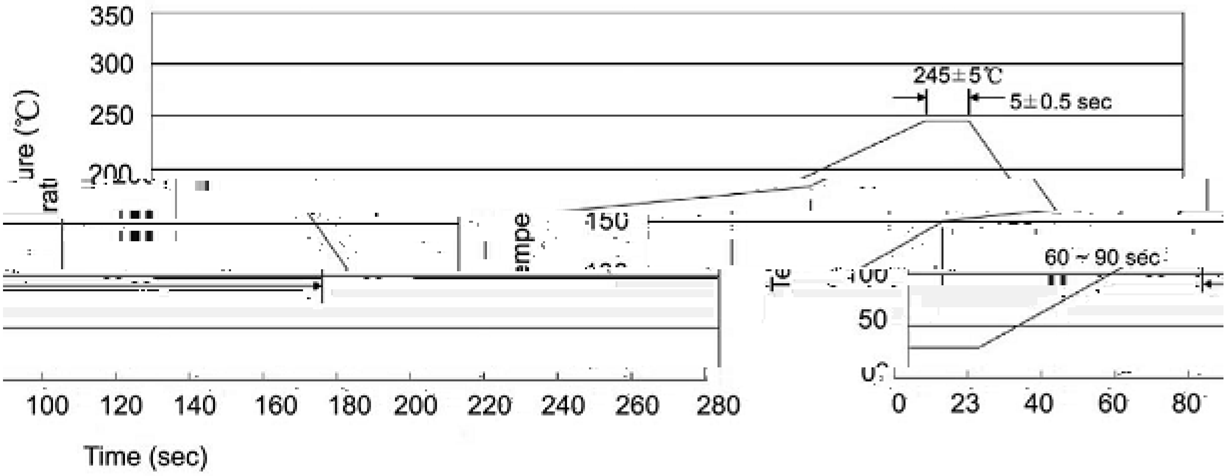
Note:

BR:	Company Code
10200	Product Type Code.
LV	TBR Process.
****:	Lot No. Code, code change with Lot No.

(　　) / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

1　　25　150　　60　90sec;
1.Preheating:25~150　, Time:60~90sec.

2　　245±5　　5±0.5sec;
2.Peak Temp.:245±5　, Duration:5±0.5sec.

3　　2　10　/sec.
3. Cooling Speed: 2~10　/sec.

/ Resistance to Soldering Heat Test Conditions

260±5　　10±1 sec.　　Temp.:260±5　　Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units	Dimension (unit mm^3)